

WHAT IS CLAIMED IS:

~~1.~~ A method for building a consumable refill, the method comprising the steps of:

 fabricating a plurality of arrays of consumable parts detachably connected along a first direction;

 stacking said plurality of said fabricated arrays of parts along a second direction; and
 providing an adhesive bond between adjacent ones of said stacked plurality of arrays.

2. The method of claim 1 wherein said fabricating step comprises the step of:
 providing a perforated connection between said consumable parts.

3. The method of claim 1 wherein said step of providing an adhesive bond
comprises the step of:

 adhering adjacent ones of said plurality of arrays using solid rub-on glue.

4. The method of claim 1 further comprising the step of:
 selecting a strength of said adhesive bond so as to allow separation of an array from
an adjacent array only upon experiencing an application of force from an array advancement
mechanism.

5. The method of claim 1 further comprising the step of:
 omitting an attachment to said adhered plurality of arrays of any material requiring
removal prior to consumption of said consumable parts in a host device.

6. The method of claim 1 further comprising the step of:
destroying the adhesive bond during consumption of the consumable parts.

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7. A staple refill, the refill comprising:
a plurality of staple wire layers stacked along a direction normal to a plane of said layers; and
an adhesive layer disposed in between each set of adjacent surfaces of said stacked staple wire layers.

8. The staple refill of claim 7 wherein said adhesive is solid adhesive.

9. The staple refill of claim 7 wherein said layers are stacked such that all staple wires of said staple wire layers are aligned.

10. The staple refill of claim 7 wherein said adhesive layers occupy substantially all of a surface area of said each set of adjacent surfaces.

11. The staple refill of claim 7 wherein said adhesive layers occupy substantially less than all of a surface area of said each set of said adjacent surfaces.

12. The staple refill of claim 7 wherein said adhesive layer has a bonding force such as to allow separation of a staple wire layer from a remainder of said refill only upon experiencing an application of force from an array advancement mechanism.

13. A system for fully consuming a staple refill, the system comprising:
means for stacking a plurality of staple wire plates; and
means for gluing together each set of adjacent staple wire plate surfaces of said
stacked plates.

14. The system of claim 13 further comprising:
means for receiving said glued stacked plates into a cartridge;
means for separating one of said glued stacked plates from a remainder of said glued
stacked plates;
means for removing a staple from said separated glued stacked plate; and
means for expelling said removed staple and any glue in contact with said removed
staple from said cartridge.

15. The system of claim 13 wherein said means for stacking comprises:
means for stacking vertically.

16. The system of claim 13 wherein said means for stacking comprises:
means for stacking said plates such that all staple wires of said stacked staple wire
plates are aligned.

17. The system of claim 13 wherein said means for gluing comprises:
means for applying glue to substantially all of a surface area of at least one of said
sets of adjacent surfaces

18. The system of claim 13 wherein said means for gluing comprises:
means for applying glue to substantially less than all of a surface area of at least one
of said sets of adjacent surfaces.

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